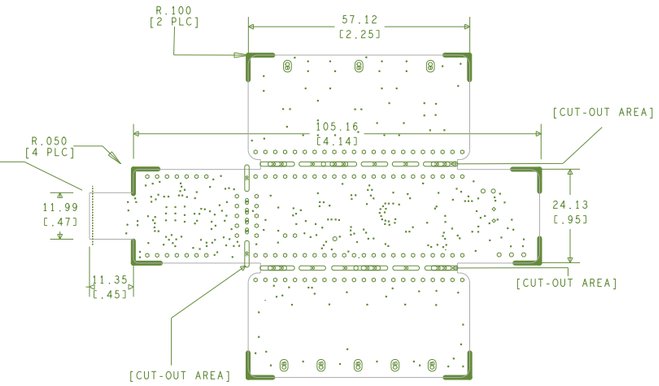
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	ALPHA RELEASE	12/18/15	AKAP
2	BETA RELEASE	12/24/15	AKAP
3	ES10 RELEASE	12/30/15	AKAP
4	ES10 RELEASE	01/01/16	AKAP
5	ES100 RELEASE	01/07/16	AKAP
6	ES100 RELEASE	01/11/16	AKAP
7	ES100 RELEASE	02/08/16	AKAP
7.1	ES100 RELEASE	02/15/16	AKAP
8	ES100 RELEASE	02/24/16	AKAP
9	ES100 RELEASE	03/05/16	AKAP
10	ES100 RELEASE	03/14/16	AKAP
11	ES100 RELEASE	04/01/16	AKAP
12	ES100 RELEASE	04/05/16	AKAP

Note: "Edge Bevelling and Chamfering at 45 degree for the USB Finger edge connector"

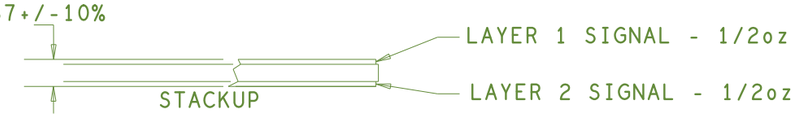


DRILL CHART: CY8CKIT-145_Rev13				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	8.0	+3.0/-3.0	PLATED	3
·	10.0	+3.0/-3.0	PLATED	201
·	13.0	+3.0/-3.0	PLATED	94
○	40.0	+3.0/-3.0	PLATED	114
○	43.0	+3.0/-3.0	PLATED	6
◦	35.4	+2.0/-2.0	NON-PLATED	2
▯	60.0x30.0	+2.0/-2.0	NON-PLATED	4
▯	120.0x80.0	+2.0/-2.0	NON-PLATED	8
▭	270.0x45.0	+2.0/-2.0	NON-PLATED	18
▯	270.0x45.0	+2.0/-2.0	NON-PLATED	2

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **RED*
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

0.0787+/-10%



UNCONTROLLED IMPEDANCE BOARD

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON; ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTIONS

CYPRESS PROPIETARY
THIS DOUCUMENT CONTAINS CONFIDENTAL, PROPRIETARY INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHIRIZED BY CYPRESS.

SIGNATURES		DATE
DRAWN	AKAP	06/24/16
CHECKED	AKAP	06/24/16
ENGRG	AKAP	06/24/16
ISSUED		

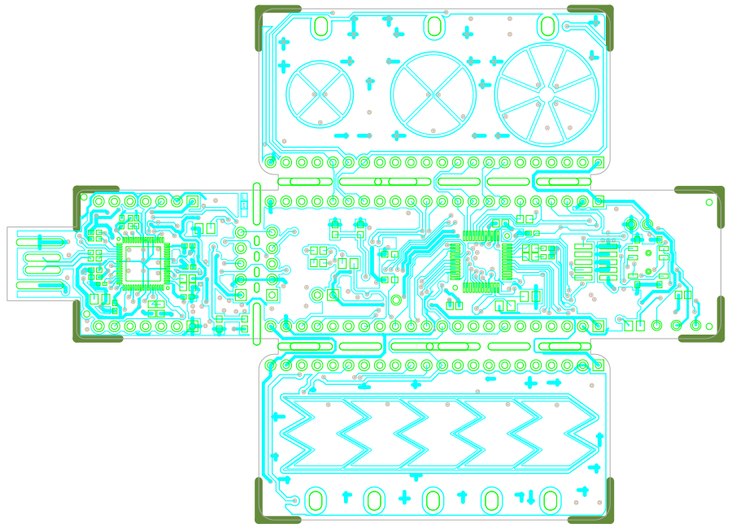
CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

FABRICATION DRAWING
CY8CKIT-145-40XX
PSoC 4000S PROTOTYPING KIT

SIZE	FSCM NO	DWG NO	REV
C		610-60295-01	12

SCALE: 1/1 SHEET: 1 OF 2

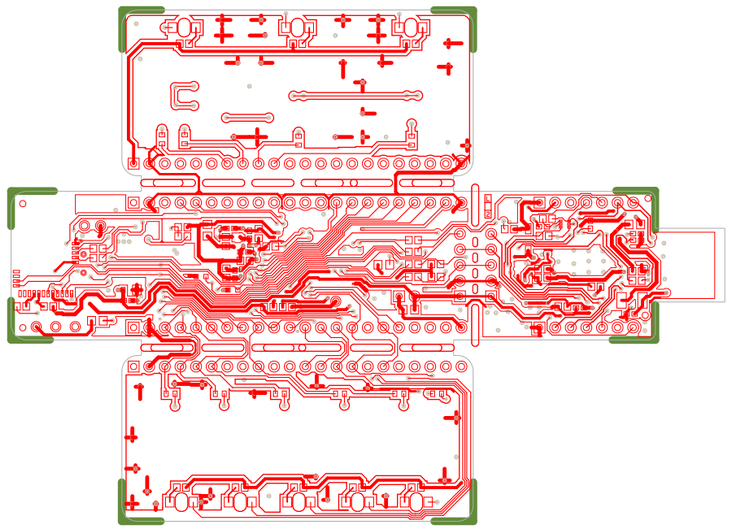
ART FILM - TOP



600-60320-01 REV12 PRIMARY SIDE

ART FILM - TOP

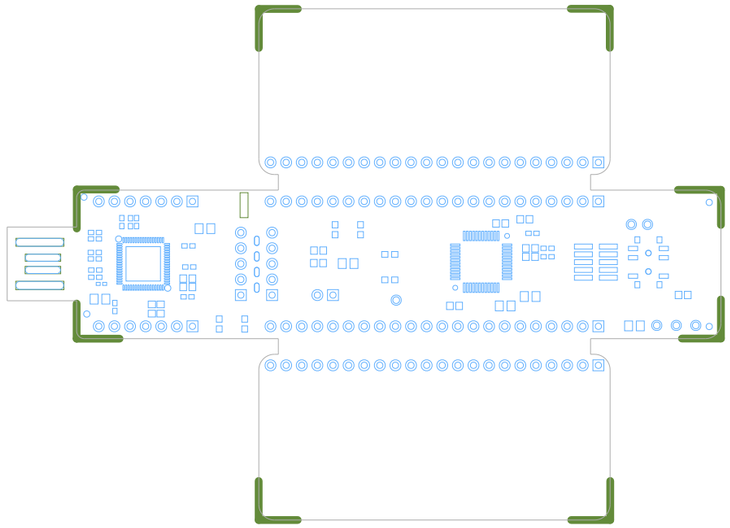
ART FILM - BOTTOM



600-60320-01 REV12 SECONDARY SIDE

ART FILM - BOTTOM

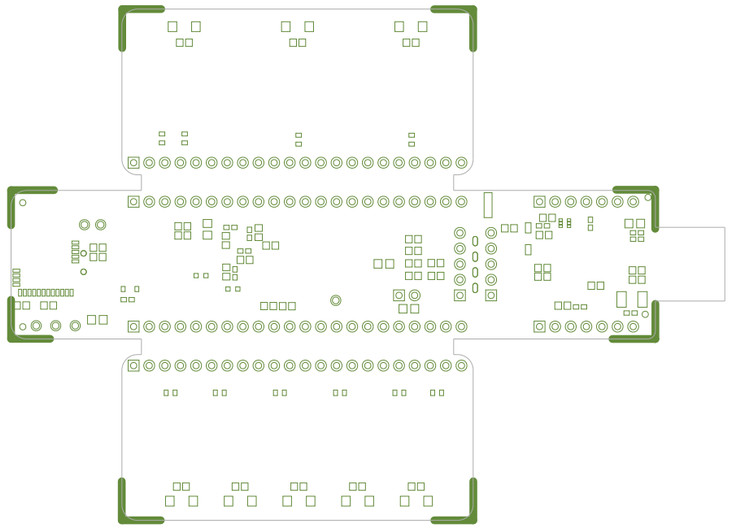
ART FILM - PSM



600-60320-01 REV12 PRIMARY SOLDERMASK

ART FILM - PSM

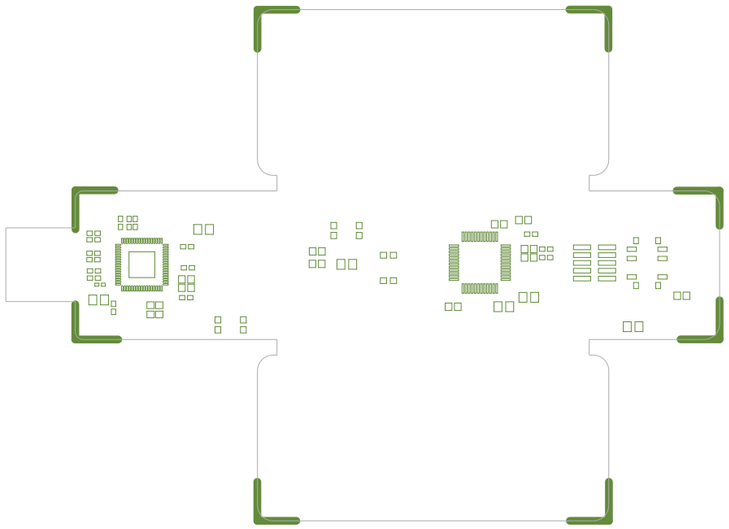
ART FILM - SSM



600-60320-01 REV12 SECONDARY SOLDERMASK

ART FILM - SSM

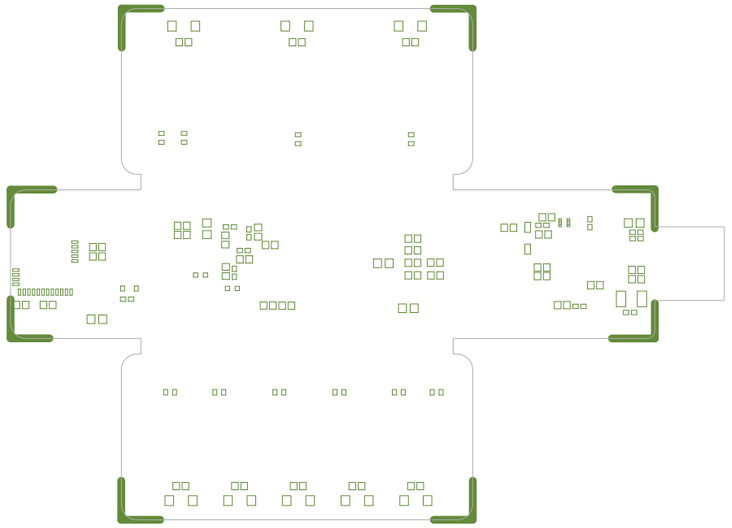
ART FILM - PSP



600-60320-01 REV12 PRIMARY SOLDERPASTE

ART FILM - PSP

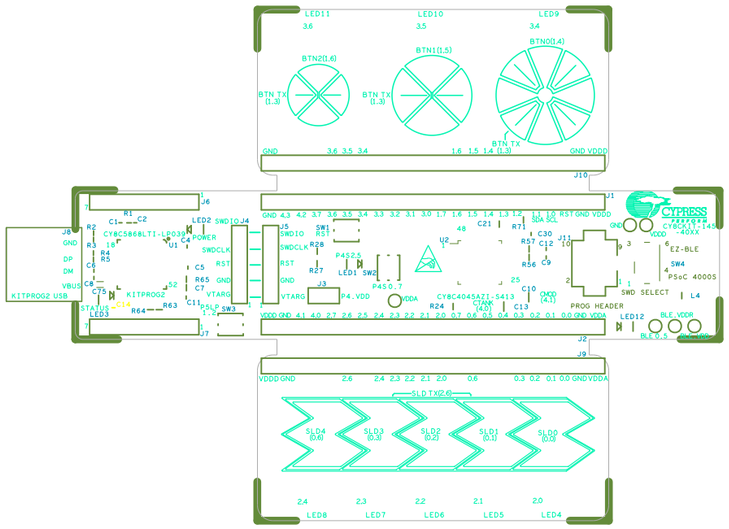
ART FILM - SSP



600-60320-01 REV12 SECONDARY SOLDERPASTE

ART FILM - SSP

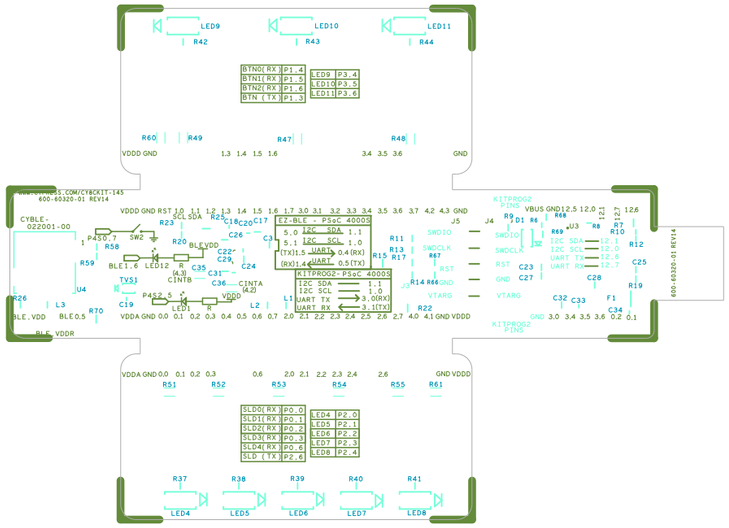
ART FILM - PSS



600-60320-01 REV12 PRIMARY SILKSCREEN

ART FILM - PSS

ART FILM - SSS



600-60320-01 REV12 SECONDARY SILKSCREEN

ART FILM - SSS